CALL FOR EXHIBITORS
SEPTEMBER 13 – 16, 2022

9th ELECTRONICS SYSTEM-INTEGRATION TECHNOLOGY CONFERENCE, SIBIU, ROMANIA

THE SINGLE LARGEST SEMICONDUCTOR PACKAGING CONFERENCE IN EUROPE

The Electronics System-Integration Technology Conference (ESTC) is the premier international event in the field of electronics packaging and system integration in Europe. The conference is organized every two years and is the IEEE-EPS flagship conference in Europe supported by IEEE-EPS in association with IMAPS-Europe. The 9th ESTC will take place in Sibiu, Romania. Placed in the middle of Romania, surrounded by the high Carpathian Mountains and Cibin river, Sibiu is a citadel of the European electronics industry and represents a place where culture, landscape, gastronomy, and profession merge in a friendly pleasant environment.

Save the date right now! - Read more about the conference and its history at www.estc-conference.net

The event brings together both scientific academics and industry leaders to present and discuss state-of-the-art and future trends in packaging and integration technologies. **ESTC is the perfect place for you to present your latest developments, promote your company or institution to the packaging community and get in contact with your existing and new customers and partners.**

DON'T MISS TO EXHIBIT at the 9th ESTC in Sibiu (Hermannstadt), Siebenbürgen, Transylvania – Home of the famous Wallachian Count Vlad III. Drăculea ("Son of the Dragon", around 1431 – 1476), who inspired Irish author Bram Stoker to the novel "Dracula", published in 1897 and one of the most famous pieces of English literature. Your chance to experience famous historic places.

AUDIENCE

The conference provides your company or institution a unique opportunity to exhibit your products and services to more than 300 engineers, managers, and decision makers from all areas of the microelectronics and system-integration industry, academics, and research institutes. These include material, equipment, software tools, design and simulation, processes and services for semiconductor assembly, interconnect, packaging, test, process control and analysis technologies as well as market research.

To meet the audience interest best, the exhibitors should focus on the following topics:

- Advanced packaging
- Optoelectronic systems packaging
- Design tools and modeling
- Advanced technologies for emerging systems
- Flexible, printed and hybrid electronics

- Materials for interconnects and packaging
- Assembly and manufacturing technologies
- Power electronics system packaging
- Reliability and quality of electronic devices and systems
- RF, mm-wave and THz systems packaging

Supporting Organizations:
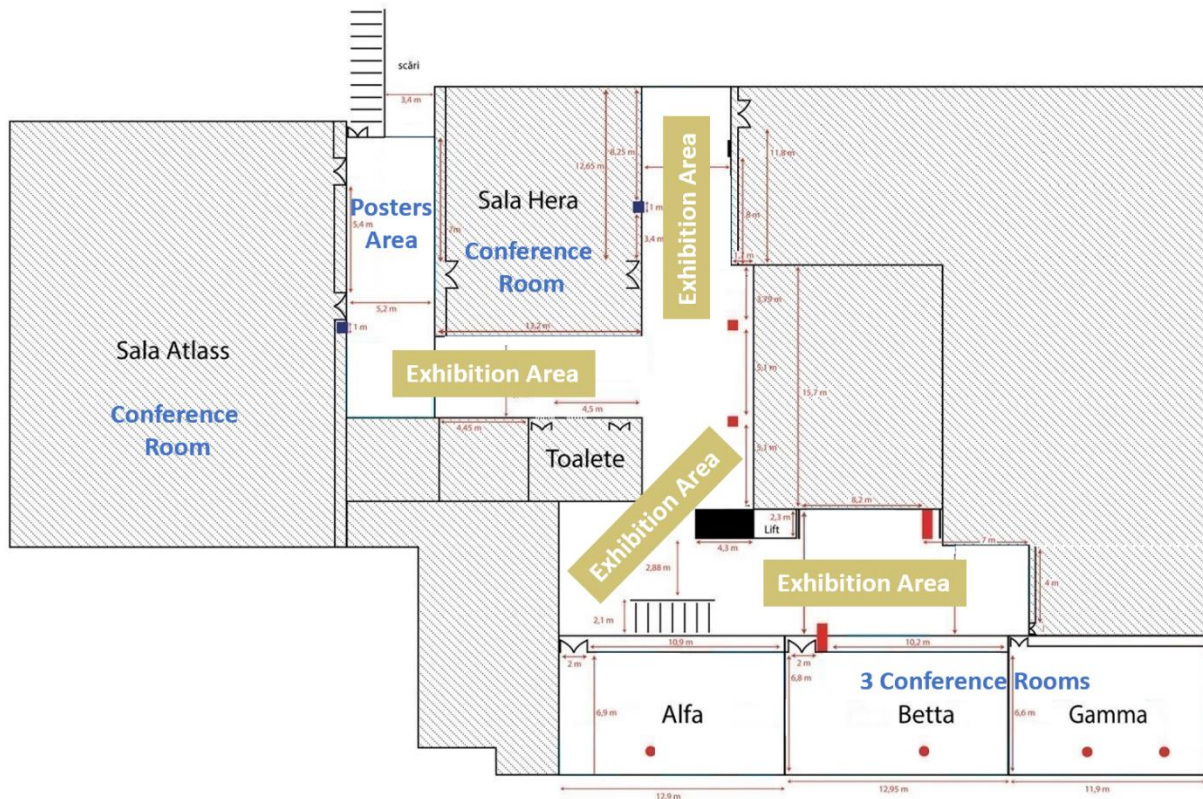
Local Organizers:

VENUE

The conference will be located at the modern Conference Center of the **RAMADA by Wyndham Sibiu Hotel,** Strada Emil Cioran 2, Sibiu 550025, Romania. The venue is easy to access, 15 minutes' drive from Sibiu International Airport.

RAMADA by Wyndham Sibiu Hotel will also be the main accommodation for the conference attendees. A rooms contingent has been reserved by the local organizers at very attractive rates.

EXHIBITION AREA

All keynotes, special sessions, technical sessions, and the interactive poster presentations as well as the coffee and lunch breaks with catering and room for intense networking will take place inside and around the exhibition area (450 m² space), which will be in the wide corridors and atrium area of the Conference Center - right in front of the doors to the conference rooms. Consequently, the exhibition area will be the focus meeting area for the conference attendees all time.

The conference will be a 3-Day-Event, where the first half day will be dedicated to Technical Short Courses / Professional Development Courses (PDCs), and the second half to invited keynotes and parallel technical sessions. The second and third days will be fully dedicated to technical sessions, special sessions and further keynotes. The exhibition schedule for the three days will be:

Tuesday, September 13th	**Wednesday, September 14th**	**Thursday, September 15th**
10:00-12:00 Setup	08:00-17:00 Exhibition	08:00-16:00 Exhibition
12:00-19:00 Exhibition		16:00-18:00 Dismantling

EXHIBITION STAND

Standard Exhibition Stand → 2.500 €
- Exhibition area 4 m² (2 m x 2 m)
- Table and chair for your company's representatives and promotional materials and/or product presentation
- Your company logo large printed and widely visible attached to your exhibition table
- 2 m space for your company branded backwall and/or roll-ups (self-delivered)
- Power supply 220 V distribution board for standard usage (laptop, lighting, charger)
- 2 complimentary conference registrations (Full Conference Rate)

Double Exhibition Stand → 4.800 €
- Exhibition area 8 m² (4 m x 2 m)
- Combination of 2 standard exhibition stands (for deliverables refer to above, space doubles)
- 2 additional complimentary conference registrations (Full Conference Rate)

Anything else needed? → Availability and cost depending on local service provider offer
- Such as spot lighting, extra furniture, showcase, brochure/flyer rack
- Extras can be inquired on early request (before 15.06.2022) only

CONTACTS TO SAVE YOUR EXHIBITION SPACE

- Steffen Kröhnert, ESPAT-Consulting Dresden, Germany: +49-(0)172-7201472, steffen.kroehnert@espat-consulting.com
- Rajmond Jano, Technical University of Cluj-Napoca, Romania: +40-(0)744-839480, rajmond.jano@ael.utcluj.ro
- Local Conference Committee: estc@estc-conference.net - Website: https://www.estc-conference.net

IMPORTANT DATES

- Website opens for abstract submission: December 1, 2021
- Abstract submission deadline: February 15, 2022
- Abstract acceptance notification: March 31, 2022
- Paper submission deadline: June 15, 2022
- Conference: September 13-16, 2022

General Chair
Paul M. Svasta
University Politehnica of Bucharest, Romania

Executive Chair
Ovidiu A. Pop
Technical University of Cluj-Napoca, Romania

Technical Program Chair
Tanja Braun
Fraunhofer IZM Berlin, Germany

Exhibition Chair
Steffen Kröhnert
ESPAT-Consulting Dresden, Germany

Supporting Organizations:

Local Organizers: